High Voltage LED Series Chip on Board

LCoogD-Gen.1

High efficacy COB LED package well-suited for use in spotlight applications

Features & Benefits

- Chip on Board (COB) solution makes it easy to design in •
- Simple assembly reduces manufacturing cost •
- Low thermal resistance •
- InGaN/GaN MQW LED with long time reliability •

Applications

- Spotlight / Downlight •
- LED Retrofit Bulbs
- Outdoor Illumination •





SAMSUNG

Table of Contents

2

1.	Characteristics	 3
2.	Product Code Information	 5
3.	Typical Characteristics Graphs	 9
4.	Outline Drawing & Dimension	 12
5.	Reliability Test Items & Conditions	 13
6.	Label Structure	 14
7.	Packing Structure	 15
8.	Precautions in Handling & Use	 17

1. Characteristics

a) Absolute Maximum Rating

ltem	Symbol	Rating	Unit	Condition
Ambient / Operating Temperature	Ta	-40 ~ +105	٥C	-
Storage Temperature	T _{stg}	-40 ~ +120	٥C	-
LED Junction Temperature	TJ	140	٥C	-
Case Temperature	Тс	105	٥C	
Forward Current	l _F	690	mA	-
Power Dissipation	P _D	25.9	W	-
ESD (HBM)	-	±2	kV	-
ESD (MM)	-	±0.5	kV	-

b) Electro-optical Characteristics $(I_F = 270 \text{ mA}, T_J = 85 \text{ }^{\circ}\text{C})$

ltem	Unit	Rank	Min.	Тур.	Max.
Forward Voltage (V_F)	V	YZ	31.8	34.6	37.5
		5	80	-	-
Color Rendering Index (R _a)	-	7	90		
Thermal Resistance (junction to chip point)	°C/W		-	1.7	-
Beam Angle	0		-	115	-
Nominal Power	W			10.1	

Notes:

1) The COB is tested in pulsed condition at rated test current (10 ms pulse width) and rated temperature ($T_J = T_C = T_a = 85 \text{ °C}$)

2) Samsung maintains measurement tolerance of: forward voltage = \pm 5 %, CRI = \pm 1

3) Refer to the derating curve, '3. Typical Characteristics Graph' designed within the range.

c) Luminous Flux Characteristics (I_F = 270 mA)

CRI (R _a)	Nominal	Flux		Flux @ T _J = 85 °C (lm)			
Min.	CCT (K)	Rank	Min.	Тур.	Max.		
	2700	H1	1149	1209	-		
		D1	1209	1270	-		
	2000	H2	1214	1278	-		
	3000	D1	1278	1342	-		
	3500	H2	1249	1315	-		
	3500	D1	1315	1381	-		
80	4000	H2	1279	1347	-		
oU		D1	1347	1414	-		
	5000	H2	1289	1357	-		
	5000	D1	1357	1425	-		
	5700	H2	1289	1357	-		
	5700	D1	1357	1425	-		
	6500	H2	1274	1341	-		
	6500	D1	1341	1408	-		

CRI (R _a)	Nominal	Flux	Flux		
Min.	CCT (K)	Rank	Min.	Тур.	Max.
	2700	G8	986	1038	-
	2700	D1	1038	1090	-
	3000	H0	1032	1087	-
		D1	1087	1141	-
90	3500	H0	1066	1122	-
90		D1	1122	1178	-
	4000	H0	1090	1147	-
	4000	D1	1147	1204	-
	5000	H1	1094	1152	-
	3000	D1	1152	1210	-

Notes:

- 1) The COB is tested in pulsed operating condition at rated test current (10 ms pulse width) and rated temperature
- $(T_J = T_C = 85 \ ^{\circ}C).$
- 2) Samsung maintains measurement tolerance of: Luminous flux = \pm 7 %, CRI = \pm 1

2. Product Code Information

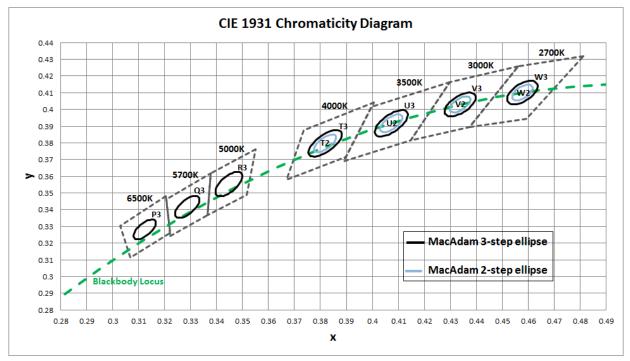
1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16	17	18
S																	

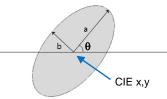
Digit	PKG Information	Code	Specification
1 2 3	Samsung Package High Power	SPH	
4 5	Color	WH	White
6	Product Version	А	
78	Form Factor	HD	СОВ
9	Lens Type	N	No lens
10	Wattage or Model	С	LC009D
11	Internal Code	2	
12	CRI & Sorting Temperature	5	Min. 80 (85°C)
12		7	Min. 90 (85°C)
13 14	Forward Voltage (V)	ΥZ	31.8~37.5
15	CCT (K)	W V U T R Q P	2700K 3000K 3500K 4000K 5000K 5700K 6500K
16	MacAdam Step	2 3	MacAdam 2-step MacAdam 3-step
17 18	Luminous Flux (Lm)	G8 H0 H1 H2 D1	980 1000 1100 1200 Add rank

a) Binning Structure (I_F = 270 mA, T_J = 85 °C)

CRI (R _a) Min.	Nominal CCT (K)	Product Code	V _F Rank	Color Rank	Flux Rank	Flux Range (Φ _v , Im)
		SPHWHAHDNC25YZW2H1		W2	H1	1149 ~
	2700	SPHWHAHDNC25YZW3H1	YZ	W3		1149 ~
	2700	SPHWHAHDNC25YZW2D1		W2	D1	1209 ~
		SPHWHAHDNC25YZW3D1		W3		1203 ~
		SPHWHAHDNC25YZV2H2		V2	H2	1214 ~
	3000	SPHWHAHDNC25YZV3H2	····· YZ	V3	112	1214~
	3000	SPHWHAHDNC25YZV2D1	12	V2	D1	1278 ~
		SPHWHAHDNC25YZV3D1		V3		1270~
		SPHWHAHDNC25YZU2H2		U2	H2	1249 ~
	3500	SPHWHAHDNC25YZU3H2	YZ	U3	112	1243 ~
80	3300	SPHWHAHDNC25YZU2D1	12	U2	D1	1315 ~
00		SPHWHAHDNC25YZU3D1		U3		
		SPHWHAHDNC25YZT2H2		T2	Ш2	1279 ~
	4000	SPHWHAHDNC25YZT3H2	YZ	Т3	H2	1279~
	4000	SPHWHAHDNC25YZT2D1	ΤZ	T2	D1	1347 ~
		SPHWHAHDNC25YZT3D1		Т3		1347 ~
	5000	SPHWHAHDNC25YZR3H2	YZ	D2	H2	1289 ~
	0000	SPHWHAHDNC25YZR3D1	ĭ∠	R3	D1	1357 ~
	5700	SPHWHAHDNC25YZQ3H2	YZ	03	H2	1289 ~
	5700	SPHWHAHDNC25YZQ3D1	Ϋ́	Q3	D1	1357 ~
	0500	SPHWHAHDNC25YZP3H2	\/7	DO	H2	1274 ~
	6500	SPHWHAHDNC25YZP3D1	YZ	P3	D1	1341 ~

CRI (R _a) Min.	Nominal CCT (K)	Product Code	V _F Rank	Color Rank	Flux Rank	Flux Range (Φ _v , Im)
		SPHWHAHDNC27YZW2G8		W2	<u></u>	000
	0700	SPHWHAHDNC27YZW3G8		W3	G8	986 ~
	2700	SPHWHAHDNC27YZW2D1	YZ	W2	D1	1038 ~
		SPHWHAHDNC27YZW3D1		W3	D1	1038 ~
		SPHWHAHDNC27YZV2H0		V2	H0	1032 ~
	3000	SPHWHAHDNC27YZV3H0	·····YZ	V3	HU	1032 ~
	3000	SPHWHAHDNC27YZV2D1		V2	D1	1087 ~
90		SPHWHAHDNC27YZV3D1		V3	DT	1087 ~
90		SPHWHAHDNC27YZU2H0		U2	H0	1066 ~
	3500	SPHWHAHDNC27YZU3H0	- YZ	U3	HU	
	3300	SPHWHAHDNC27YZU2D1		U2	D1	1122 ~
		SPHWHAHDNC27YZU3D1		U3		1122 ~
		SPHWHAHDNC27YZT2H0	_	T2	H0	1090 ~
	4000	SPHWHAHDNC27YZT3H0	- YZ	T3	110	1090 ~
	4000	SPHWHAHDNC27YZT2D1		T2	D1	1147 ~
		SPHWHAHDNC27YZT3D1		T3	יט	1147~
	5000	SPHWHAHDNC27YZR3H1	- YZ	R3	H1	1094 ~
	5000 SPHWHAHDNC27YZR3D1		Ϋ́	R3	D0	1152 ~





MacAdam Ellipse (W2, W3)										
Step	CIE x	CIE y								
2-step	0.4578	0.4101	53.70	0.0054	0.0028					
3-step	0.4578	0.4101	53.70	0.0081	0.0042					

MacAdam Ellipse (U2, U3)									
Step	CIE x	CIE y							
2-step	0.4073	0.3917	54.00	0.0062	0.0028				
3-step	0.4073	0.3917	54.00	0.0093	0.0041				

MacAdam Ellipse (R3)									
Step CIE x CIE y θ a b									
3-step	0.3447	0.3553	59.62	0.0082	0.0035				

MacAdam Ellipse (P3)						
Step CIE x		CIE y				
3-step	0.3123	0.3282	58.5700	0.0067	0.0029	

MacAdam Ellipse (V2, V3) Step CIE x CIE y θ a b 2-step 0.4338 0.403 53.22 0.0056 0.0027 3-step 0.4338 0.4030 53.22 0.0083 0.0041

MacAdam Ellipse (T2, T3)						
Step	CIE x	CIE y				
2-step	0.3818	0.3797	53.72	0.0063	0.0027	
3-step	0.3818	0.3797	53.72	0.0094	0.0040	

MacAdam Ellipse (Q3)						
Step	CIE x	CIE y				
3-step	0.3287	0.3417	59.0950	0.0075	0.0032	

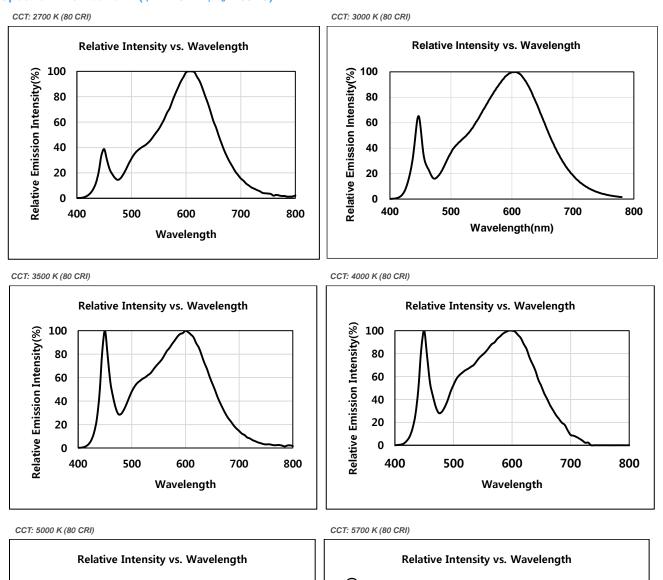
Note:

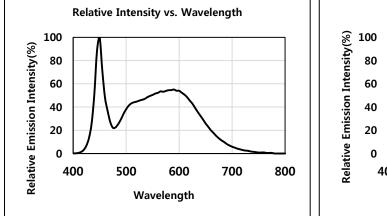
Samsung maintains measurement tolerance of: $Cx, Cy = \pm 0.005$

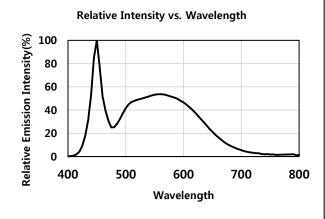
8

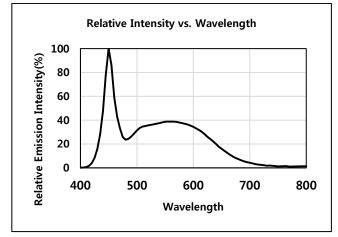
3. Typical Characteristics Graphs

a) Spectrum Distribution ($I_F = 270 \text{ mA}, T_J = 85 \text{ }^{\circ}\text{C}$)

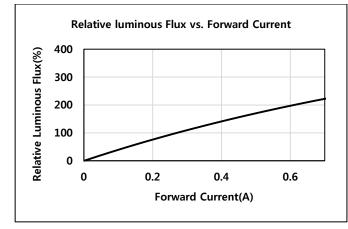




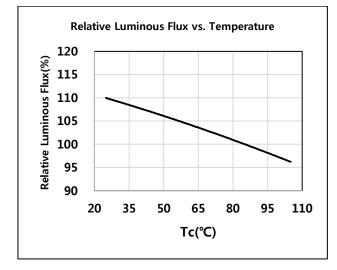


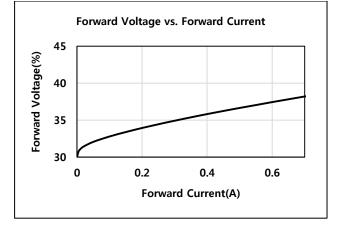


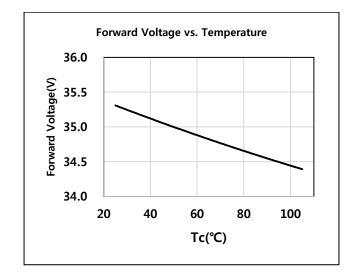
b) Forward Current Characteristics (T_J = 85 °C)



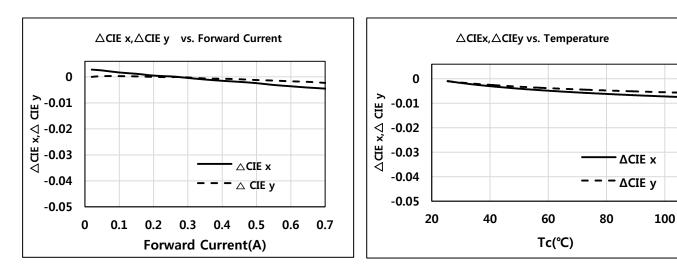
C) Temperature Characteristics (I_F = 270mA)



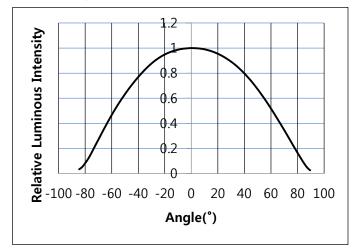




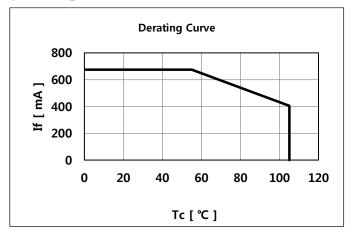
d) Color Shift Characteristics (T_J = 25 °C, I_F = 270mA, CRI80+)



e) Beam Angle Characteristics (IF = 270 mA, TJ = 85 °C)

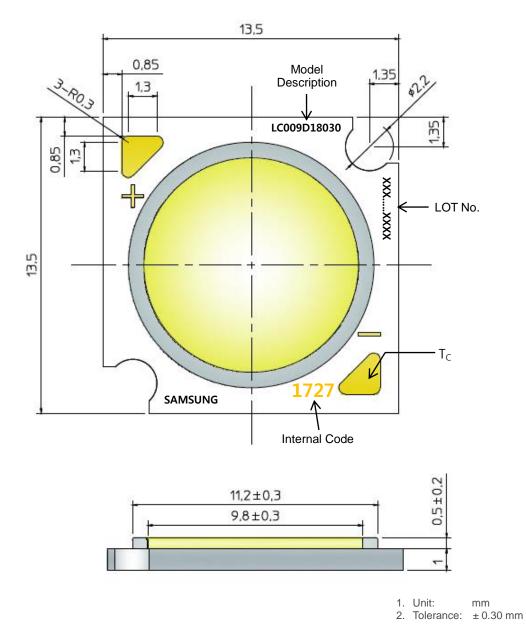


f) Derating Characteristics





4. Outline Drawing & Dimension



Length 13.5 ±0.15 mm Width 13.5 ±0.15 mm Height 1.50 ±0.20 mm Light Emitting Surface (LES) Diameter 9.8 ±0.30 mm

Note: Denoted product information above is only an example (LC009D18030 : LC009D, CRI80+, 3000K)

5. Reliability Test Items & Conditions

a) Test Items

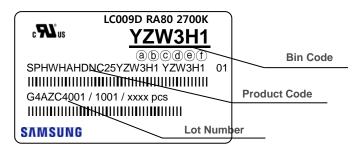
Test Item	Test Condition	Test Hour / Cycle
High Temperature Humidity Life Test	60 °C, 90 % RH,, DC Derating, $\rm I_F$	1000 h
High Temperature Life Test	85 °C, DC Derating, I _F	1000 h
Low Temperature Life Test	-40 °C, DC , I_{F} = 480 mA	1000 h
Pulsed Operating Life Test	55 $^{\circ}\text{C},$ Pulse width 100 $\mu\text{s},$ duty cycle 3 $\%$	1000 h
High Temperature Storage	120 °C	1000 h
Low Temperature Storage	-40 °C	1000 h
Temperature Humidity Storage	60 °C, 90% RH	1000h
Temperature Cycle On/Off Test	-40 °C / 85 °C each 20 min, 30 min transfer power on/off each 5 min, DC Derating, $\rm I_F$ = max	100 cycles
ESD (HBM)	R ₁ : 10 MΩ R ₂ : 1.5 kΩ C: 100 pF V: ±2 kV	5 times
ESD (MM)	R ₁ : 10 MΩ R ₂ : 0 kΩ C: 200 pF V: ±0.2 kV	5 times
Vibration Test	20 ~ 80 Hz (displacement: 0.06 inch, max. 20 g) 80 ~ 2 kHz (max. 20 g) min. frequency ↔ max. frequency 4 min transfer	4 times
Mechanical Shock Test	1500 g, 0.5 ms each of the 6 surfaces (3 axis x 2 sides)	5 times
Sulfur Resistance	25 °C, 75%, H2S 15 ppm	504h

b) Criteria for Judging the Damage

ltem	Symbol	Test Condition	Lin	Limit		
item	Symbol	(T _c = 25 °C)	Min.	Max.		
Forward Voltage	V _F	$I_F = 270 \text{ mA}$	L.S.L. * 0.9	U.S.L. * 1.1		
Luminous Flux	Φν	I _F = 270 mA	L.S.L * 0.7	U.S.L * 1.3		

6. Label Structure

a) Label Structure



Note: Denoted bin code and product code above is only an example (see description on page 5)

Bin Code:

- (a) (b): Forward Voltage bin (refer to page 11)
- ©d: Chromaticity bin (refer to page 9-10)
- (e) f): Luminous Flux bin (refer to page 6)

b) Lot Number

The lot number is composed of the following characters:

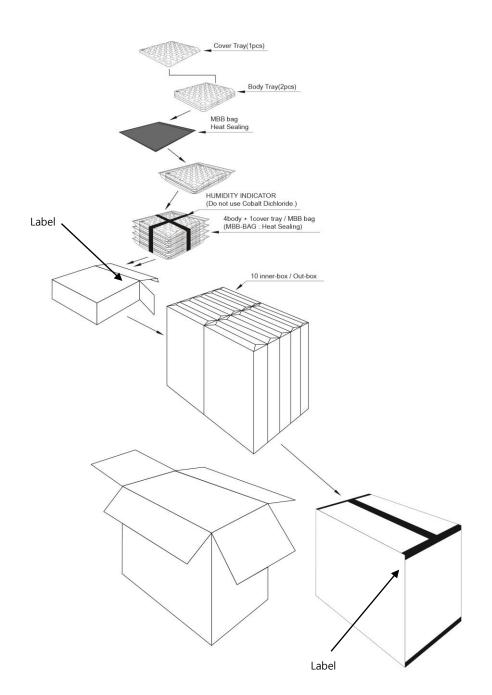


- 1 3456789 / 1abc / xxxx pcs
- (1) : Production site (S: Giheung, Korea, G: Tianjin, China)
- ② : 4 (LED)
- ③ : Product state (A: Normal, B: Bulk, C: First Production, R: Reproduction, S: Sample)
- (4) : Year (Z: 2015, A: 2016, B: 2017...)
- (5) : Month (1~9, A, B, C)
- 6789 : Day (1~9, A, B~V)
- (a)b)c) : Product serial number (001 ~ 999)

7. Packing Structure

	Max. quantity	Dimension(mm)				
Packing material	in pcs of COB	Length	Width	Height	Tolerance	
Tray	30	160	180	10	1.0	
Aluminum Bag	6o(2 trays)	210	241		10	
Inner Box	240	230	84	260	2	
Outer Box	2400	476	445	272	5	

a) Packing Structure

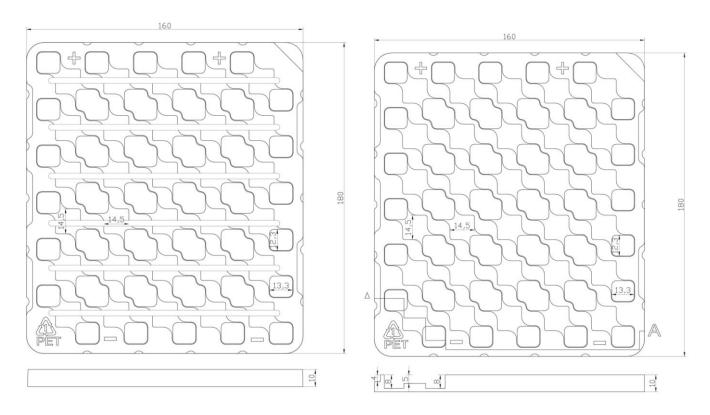


15

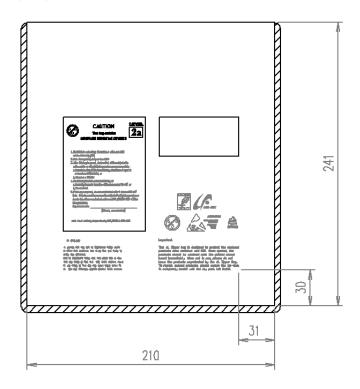
b) Tray

1 Cover

② Body

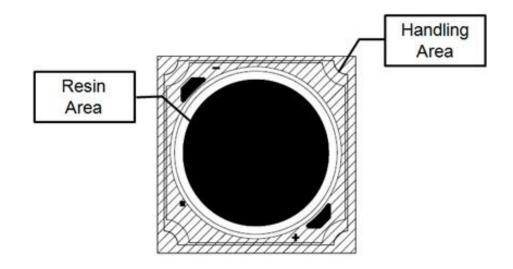


c) Aluminum Vinyl Packing Bag



8. Precautions in Handling & Use

- This device should not be used in any type of fluid such as water, oil, organic solvent, etc. When cleaning is required, IPA is recommended as the cleaning agent. Some solvent-based cleaning agent may damage the silicone resins used in the device.
- 2) LEDs must be stored in a clean environment. If the LEDs are to be stored for three months or more after being shipped from Samsung, they should be packed with a nitrogen-filled container (shelf life of sealed bags is 12 months at temperature 0~40 °C, 0~90 % RH).
- After storage bag is opened, device subjected to soldering, solder reflow, or other high temperature processes must be:
 a. Mounted within 672 hours (28 days) at an assembly line with a condition of no more than 30 °C / 60 % RH, or
 b. Stored at <10 % RH
- 4) Repack unused products with anti-moisture packing, fold to close any opening and then store in a dry place.
- 5) Devices require baking before mounting, if humidity card reading is >60 % at 23 ± 5 °C.
- 6) Devices must be baked for 1 hour at 60 ± 5 °C, if baking is required.
- 7) The LEDs are sensitive to the static electricity and surge current. It is recommended to use a wrist band or antielectrostatic glove when handling the LEDs. If voltage exceeding the absolute maximum rating is applied to LEDs, it may cause damage or even destruction to LED devices. Damaged LEDs may show some unusual characteristics such as increase in leakage current, lowered turn-on voltage, or abnormal lighting of LEDs at low current.
- The thermal management is one of the most critical factors for the LED lighting system. Especially the LED junction temperature should not exceed the absolute maximum rating while operation of LED lighting system.
 For more information, please refer to Application Note 'Mechanical & Thermal Guide for COB'.
- 9) In case of driving LEDs around the minimum current level (If_min), chips might exhibit different brightness due to the variation in I-V characteristics of each one. This is normal and does not adversely affect the performance of product.
- 10) VOCs (Volatile Organic Compounds) can be generated from adhesives, flux, hardener or organic additives used in luminaires (fixtures). Transparent LED silicone encapsulant is permeable to those chemicals and they may lead to a discoloration of encapsulant when they exposed to heat or light. This phenomenon can cause a significant loss of light emitted (output) from the luminaires. In order to prevent these problems, we recommend users to know the physical properties of materials used in luminaires and they must be carefully selected.
- 11) The resin area is very sensitive, please do not handle, press, touch, rub, clean, or pick by with tweezers on it. Instead, please pick at the handling area as indicated below.



About Samsung Electronics Co., Ltd.

Samsung Electronics Co., Ltd. inspires the world and shapes the future with transformative ideas and technologies, redefining the worlds of TVs, smartphones, wearable devices, tablets, cameras, digital appliances, printers, medical equipment, network systems and semiconductors. We are also leading in the Internet of Things space through, among others, our Digital Health and Smart Home initiatives. We employ 307,000 people across 84 countries. To discover more, please visit our official website at www.samsung.com and our official blog at global.samsungtomorrow.com.

Copyright © 2015 Samsung Electronics Co., Ltd. All rights reserved. Samsung is a registered trademark of Samsung Electronics Co., Ltd. Specifications and designs are subject to change without notice. Non-metric weights and measurements are approximate. All data were deemed correct at time of creation. Samsung is not liable for errors or omissions. All brand, product, service names and logos are trademarks and/or registered trademarks of their respective owners and are hereby recognized and acknowledged.

Samsung Electronics Co., Ltd. 95, Samsung 2-ro Giheung-gu Yongin-si, Gyeonggi-do, 446-711 KOREA

www.samsungled.com

SAMSUNG